

SEMICAPS 3000

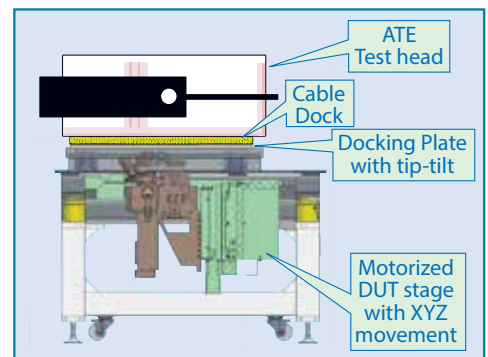
DIRECT TESTER-DOCKED SYSTEM

Dynamic
Device
Analysis



Features

- For backside analysis of wafers, wafer parts and packaged devices. Able to dock with all ATE platforms
- Easily moved from Tester to Tester
- Custom docking for all ATE platforms
- High resolution stage with 0.5 μm repeatability
- Centric and Aplanatic Refractive Solid Immersion Lens (RSIL) option
- CAD interface option
- Compatible with thermal management solutions
- Techniques include a combination of:
 - Laser Timing Probe (LTP)
 - Scanning Optical Microscopy (SOM) with best sensitivity
 - static: TIVA, OBIRCH
 - dynamic: LADA, SDL
 - Photon Emission Microscopy (PEM) with various options for the InGaAs or Si-CCD camera
 - Thermal Microscopy (THM) with InSb camera



ATE-Docked

SEMICAPS
Excellence In Innovation

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